

Product Brief

MPC533PB/D Rev. 0, 2/2003

MPC533/MPC534 Product Brief



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This document provides an overview of the MPC533/MPC534 microcontroller, including a block diagram showing the major modular components, sections that list the major features, and differences between the MPC533 and the MPC555. The MPC533 and MPC534 devices are members of the Motorola MPC500 RISC Microcontroller family. The parts herein will be referred to only as MPC533 unless specific parts need to be referenced.

Table 1. MPC533/MPC534 Features

Device	Flash	Code Compression	
MPC533	512 Kbytes	Code compression not supported	
MPC534	512 Kbytes	Code compression supported	

1 Introduction

The MPC533 device offers the following features:

- 32-bit single issue $PowerPC^{TM}$ core
- Unified system integration unit (USIU) with a flexible memory controller and enhanced interrupt controller (EIC)
- 64-bit floating-point unit (FPU)
- 512-Kbytes of Flash EEPROM memory
 - Typical endurance of 100,000 write/erase cycles @ 25°C
 - Typical data retention of 100 years @ 25°C
- 32-Kbytes of static RAM in one CALRAM module, configured as
 - 28-Kbyte normal access only array
 - 4-Kbyte normal access or overlay access array (eight 512-byte regions)
- One 22-timer channel modular I/O system (MIOS14)
- One TouCAN module (TouCAN B)
- Enhanced queued analog system (QADC64E)
- One queued serial multi-channel module (QSMCM), which contains one queued serial peripheral interface (QSPI) and two serial controller interfaces (SCI/UART)
- One peripheral pin multiplexing module (PPM) with a parallel to serial driver

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3lock Diagram

- Debug features:
 - Nexus debug port (Level 3)
 - Background debug mode (BDM)
 - IEEE1194.1 compliant interface (JTAG)
- Plastic ball grid array (PBGA) packaging
 - 388 ball PBGA
 - 27 mm x 27 mm body size
 - 1.0 mm ball pitch
 - 40-MHz operation
- -40°C-85°C

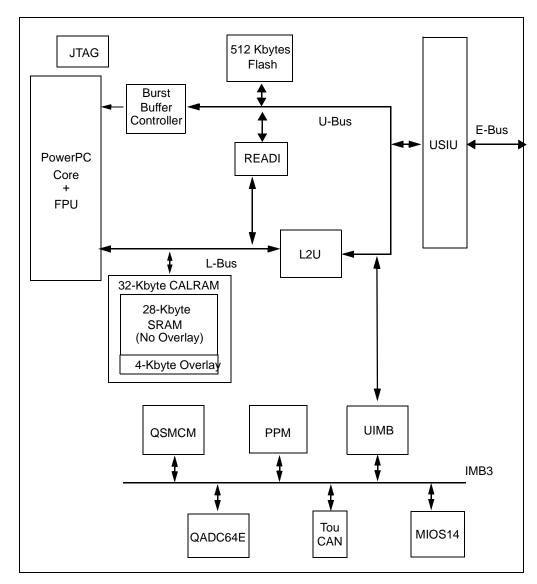
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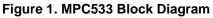
- Two power supplies
 - 5-V I/O (5.0 ± 0.25 V)
 - 2.6 ± 0.1 -V external bus with a 5-V tolerant I/O system
 - 2.6 ± 0.1 -V internal logic
 - IRAMSTBY on-chip voltage regulator

1.1 Block Diagram

Figure 1 is a block diagram of the MPC533.







1.2 Key Features

The MPC533 key features are explained in the following sections.

1.2.1 High Performance CPU System

- Fully static design
- Four major power saving modes
 - On, doze, sleep, deep-sleep, and power-down



Key Features

1.2.1.1 RISC MCU Central Processing Unit (RCPU)

- 32-bit single issue PowerPC core
- Precise exception model
- 64-bit floating point unit (FPU)
- Code compression supported on MPC534
 - Reduces usage of internal/external Flash memory (up to 50% for code)
 - The code compression feature is optimized for automotive (non-cached) applications
- Extensive system development support
 - On-chip watchpoints and breakpoints
 - Program flow tracking

1.2.1.2 MPC500 System Interface (USIU)

- System configuration and protection features:
 - Periodic-interrupt timer
 - Bus monitor
 - Software watchdog timer
 - Real-time clock (RTC)
 - PPC decrementer
 - Time base
- Clock synthesizer
- Power management
- Reset controller
- External bus interface that tolerates 5-V inputs, provides 2.6-V outputs, and supports multiple-master designs
- Enhanced interrupt controller that supports up to eight external and 40 internal interrupts, simplifies the interrupt structure, and decreases interrupt processing time
- USIU supports dual mapping to map part of one internal/external memory to another external memory
- External bus, supporting non-wraparound burst for instruction fetches, with up to 8 instructions per memory cycle

1.2.1.3 Burst Buffer Controller (BBC) Module

- Support for enhanced interrupt controller (EIC)
- Support for enhanced exception table relocation feature
- Branch target buffer
- Contains 2 Kbytes of decompression RAM (DECRAM) for code compression. This RAM may also be used as general-purpose RAM when code compression feature not used.



1.2.1.4 Flexible Memory Protection Unit

- Flexible memory protection units (MPU) in BBC and L2U
- Default attributes available in one global entry
- Attribute support for speculative accesses
- Up to eight memory regions are supported, four for data and four for instructions

1.2.1.5 Memory Controller

- Four flexible chip selects via memory controller
- 24-bit address and 32-bit data buses
- 4-Kbyte to one 16-Mbyte (data) or 4-Gbyte (instruction) region size support
- Supports enhanced external burst
- Up to eight-beat transfer bursts, two-clock minimum bus transactions
- Use with SRAM, EPROM, flash and other peripherals
- Byte selects or write enables
- 32-bit address decodes with bit masks
- Four regions

1.2.1.6 512-Kbytes of CDR3 Flash EEPROM Memory (UC3F)

- One 512-Kbyte module
- Page read mode
- Block (64 Kbytes) erasable
- External 4.75- to 5.25-V VFLASH power supply for program, erase, and read operations
- Typical endurance of 100,000 write/erase cycles @ 25°C
- Typical data retention of 100 years @ 25°C

1.2.1.7 32-Kbyte Static RAM (CALRAM)

- Composed of one 32-Kbyte CALRAM module
 - 28-Kbyte static RAM
 - 4-Kbyte calibration (overlay) RAM feature that allows calibration of flash-based constants
- Eight 512-byte overlay regions
- One clock fast accesses
- Two clock cycle access option for power saving
- Keep-alive power (IRAMSTBY) for data retention

1.2.1.8 General Purpose I/O Support (GPIO)

- 24 address pins and 32 data pins can be used for general-purpose I/O in single-chip mode
- 16 GPIO in MIOS14
- Many peripheral pins can be used as GPIO when not used as primary functions
- 2.6-V outputs on external bus pins
- 5-V outputs with slew rate control



Key Features

1.2.2 Nexus Debug Port (Class 3)

- Compliant with Class 3 of the IEEE-ISTO 5001-1999
- Program trace via branch trace messaging (BTM)
- Data trace via data write messaging (DWM) and data read messaging (DRM)
- Ownership trace via ownership trace messaging (OTM)
- Run-time access to on-chip memory map and special purpose registers (SPRs) via the READI read/write access protocol
- Watchpoint messaging via the auxiliary port
- 9 or 16 full-duplex auxiliary pin interface for medium and high visibility throughput
- All features configurable and controllable via the auxiliary port
- Security features for production environment
- Supports the RCPU debug mode via the auxiliary port
- READI module can be reset independent of system reset

1.2.3 Integrated I/O System

1.2.3.1 22-Channel Modular I/O System (MIOS14)

- Six modulus counter sub-modules (MCSM)
- 10 double-action sub-modules (DASM)
- 12 dedicated PWM sub-modules (PWMSM)
- One MIOS14 16-bit parallel port I/O sub-modules (MPIOSM)

1.2.3.2 Enhanced Queued Analog-to-Digital Converter Module (QADC64E)

- Queued analog-to-digital converter module (QADC64E_A) providing a total of 16 analog channels using internal multiplexing
- Directly supports up to four external multiplexers
- Up to 41 total input channels on the QADC64E module with external multiplexing
- Software configurable to operate in enhanced or legacy (MPC555 compatible) mode
- Unused analog channels can be used as digital input/output pins
- GPIO on all channels in enhanced mode
- 10-bit A/D converter with internal sample/hold
- Typical conversion time of less than 5 μ s (>200 K samples/second)
- Two conversion command queues of variable length
- Automated queue modes initiated by:
 - External edge trigger
 - Software command
 - Periodic/interval timer within QADC64E module, that can be assigned to both queue 1 and 2
 - External gated trigger (queue 1 only)
- 64 result registers
 - Output data is right- or left-justified, signed or unsigned.
- Alternate reference input (ALTREF), with control in the conversion command word (CCW)

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1.2.3.3 One CAN 2.0B Controller (TouCAN) Module

- One TouCAN module (TouCAN B)
- TouCAN provides the following features:
 - 16 message buffers, programmable I/O modes
 - Maskable interrupts
 - Independent of the transmission medium (external transceiver is assumed)
 - Open network architecture, multi-master concept
 - High immunity to EMI
 - Short latency time for high-priority messages
 - Low-power sleep mode, with programmable wake-up on bus activity

1.2.3.4 Queued Serial Multi-Channel Module (QSMCM)

- One queued serial module with one queued SPI and two SCIs (QSMCM)
- QSMCM matches full MPC555 QSMCM functionality
- Queued SPI
 - Provides full-duplex communication port for peripheral expansion or inter-processor communication
 - Up to 32 preprogrammed transfers, reducing overhead
 - Synchronous serial interface with baud rate of up to system clock / 4
 - Four programmable peripheral-selects pins:
 - Support up to 16 devices with external decoding
 - Support up to eight devices with internal decoding
 - Special wrap-around mode allows continuous sampling of a serial peripheral for efficient interfacing to serial analog-to-digital (A/D) converters
- SCI
 - UART mode provides NRZ format and half- or full-duplex interface
 - 16 register receive buffers and 16 register transmit buffers on one SCI
 - Advanced error detection and optional parity generation and detection
 - Word-length programmable as eight or nine bits
 - Separate transmitter and receiver enable bits, and double buffering of data
 - Wake-up functions allow the CPU to run uninterrupted until either a true idle line is detected, or a new address byte is received

1.2.3.5 Peripheral Pin Multiplexing (PPM)

- Synchronous serial interface between the microprocessor and an external device
- Two internal parallel data sources can be multiplexed through the PPM
 - MIOS14: 12 PWM channels, four MDA channels
 - Internal GPIO: 16 general-purpose inputs, 16 general-purpose outputs
- Software configurable stream size
- Software configurable clock (TCLK) based on system clock
- Software selectable clock modes (SPI mode and TDM mode)

.MPC533 Optional Features

- Software selectable operation modes
 - Continuous mode
 - Start-transmit-receive (STR) mode
- Software configurable internal modules interconnect (shorting)

1.3 MPC533 Optional Features

The following features of the MPC533 are optional features and may not appear in certain configurations:

Code compression on MPC534

2 Comparison of MPC533 and MPC555

The MPC533 is a derivative of the MPC555. Most functional features of the MPC555 are unchanged on the MPC533. Refer to Table 2 for a comparison of features.

Module	MPC555	MPC533	
CPU Core	Ide	Identical	
BBC	Basic	Enhanced Code Compression (classes scheme with 2 Kbytes DECRAM) Code Compression is available only on MPC534.	
L2U	Identical		
SRAM	26 Kbytes	32 Kbytes calibration SRAM with overlay features	
Flash	448-Kbyte CMF (2 modules, 256-Kbyte and 192-Kbyte)	512-Kbyte UC3F (1 module)	
USIU	Basic	Enhanced Interrupt Controller	
JTAG	Selectable by RCW	Selectable at PORESET	
READI	None	New Debut Module (Class 3 Nexus IEEE-ISTO 5001-1999)	
UIMB	Identical		
QADC64	(2)	(1) Enhanced	
QSMCM	(1) Identical (1)		
MIOS	MIOS1	MIOS14 4 Extra PWMSM 4 Extra MCSM no Real-Time Clock	
TouCAN	(2) Identical (1)		
PPM	_	New Module	

Table 2. Differences Between MPC555 and MPC533



2.1 Additional MPC533 Differences

- The MPC533 is very similar to the MPC555 with the following differences:
 - CDR3 technology
 - Two power supplies: 5.0-V I/O, 2.6-V external bus pins, 2.6-V internal logic
 - New modules: READI, CALRAM, PPM
 - One less TouCAN module, 6 Kbytes extra of SRAM on L-bus (32 Kbytes total) (with CALRAM overlay features)
- QADC64
 - GPO on all channel pins in addition to GPI functions
- TouCAN, QSMCM, UIMB, Core, L2U
 - No changes
- BBC
 - Enhanced interrupt controller support
 - Enhanced exception relocation table
 - Branch target buffer
 - 2 Kbytes of decompression RAM for code compression. This may also be used as general-purpose RAM while not used for code compression.
- CALRAM (with overlay features)
 - New module
 - Overlay features allow calibration of Flash-based constants
- UC3F (U-bus CDR3 Flash module)
 - 512 Kbytes of non-volatile memory (NVM)
 - Designed for use in embedded microcontroller (MCU) applications targeted for high speed read performance and high density byte count requirements
- READI
 - New module
- USIU
 - Enhanced interrupt controller
 - ENGCLK default frequency
 - READI support
 - Reduced data setup time
 - Enhanced external burst support
- MIOS14
 - Four additional PWM channels
 - Four additional MCSM timers
- PPM (peripheral pin multiplexing)
 - New module
 - Two-to-one multiplexing
 - Parallel to serial (SPI and TDM)

Additional MPC533 Differences

3 SRAM Keep-Alive Power Behavior

One keep-alive power pin (IRAMSTBY) provides keep-alive power to RAM.

The IRAMSTBY pin can be powered directly from a battery using an internal shunt regulator or via a small battery for standby use. See Figure 2.

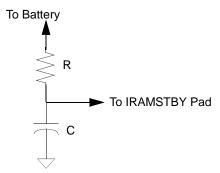


Figure 2. Recommended Connection Diagram for IRAMSTBY

While power is off to the MPC533, the IRAMSTBY supply powers the following:

- 32-Kbyte CALRAM
- 2-Kbyte BBC DECRAM module

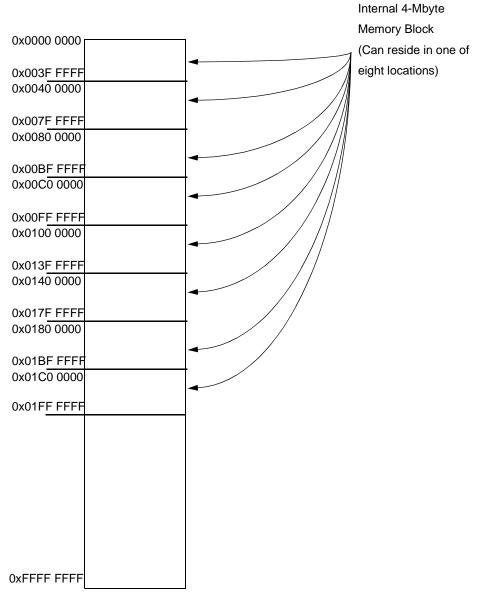
4 MPC533 Address Map

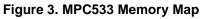
The internal memory map is organized as a single 4-Mbyte block. The user can assign this block to one of eight locations by programming a register in the USIU (IMMR[ISB]). The eight possible locations are the first eight 4-Mbyte memory blocks starting with address 0x0000 0000 (refer to Figure 3). The programmability of the internal memory map location allows the user to implement a multiple-chip system.

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The internal memory space is divided into the following sections. Refer to Figure 4.

- Flash memory (512-Kbytes)
- CALRAM static RAM memory (32-Kbytes)
- Control registers and IMB3 modules (64 Kbytes)
 - BBC control registers (16-Kbytes)
 - USIU and Flash control registers (16-Kbytes)
 - UIMB interface and IMB3 modules (32-Kbytes)
 - CALRAM/READI control registers (256-bytes)

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0x00 0000	UC3F Flash					
	512 Kbytes					
0x07 FFFF 0x08 0000	-	† /		0x2F C000		
			USIU Control Registers			
	Reserved for Flash					
	2,605 Kbytes					
			UC3F Control	0x2F C800		
0x2F 7FFF			Registers			
0x2F 7FFF 0x2F 8000	BBC DECRAM 2 Kbytes		<u> </u>			
0x2F 8800	Reserved for BBC		Reserved* (32 bytes)	0x30 0000		
0x2F A000 0x2F BFFF	BBC CONTROL			0x30 0020		
0x2F C000			Reserved (8160 bytes)			
	USIU & Flash Control					
0x2F FFFF	16 Kbytes			0x30 2000		
0x30 0000	UIMB I/F & IMB	1		0,000 2000		
	Modules		Reserved* (10 Kbytes)			
0x30 7FFF	32 Kbytes					
0x30 8000	Reserved for IMB			0x30 4400		
0x37 FFFF	491 Kbytes		QADC64 A (1 Kbyte)	0x30 4800		
0x38 0000		1 \		0x30 4C00		
	CALRAM/ READI Control		Reserved* (1 Kbyte)	0,00 +000		
0x38 00FF	256 bytes		QSMCM (1 Kbyte)	0x30 5000		
0x38 0100	Reserved (L-bus Control)			0x30 5400		
0x38 3FFF	~32 Kbytes		Reserved (2 Kbytes)	0,00 0400		
0x38 4000		† \ †	PPM (64 bytes)	0x30 5C00		
			Reserved (960 bytes)	0x30 5C80		
	Reserved (L-bus Mem)		····			
	464 Kbytes		MIOS14 (4 Kbytes)	0x30 6000		
0x3F 7FFF						
0x3F 8000						
	CALRAM		Reserved* (1 Kbyte)	0x30 7000		
0735 5000	32 Kbytes			0x30 7400		
0x3F F000		1 \ 4	TouCAN B (1 Kbyte)			
0x3F FFFF	4-Kbyte Overlay Section		Reserved* (1 Kbyte)	0x30 7800 0x30 7900		
Reserved (896 bytes)						
*NOTE:	Reserved, do not write to the	UIMB Registers	0x30 7F80			
		V				

Figure 4. MPC533 Internal Memory Map

(128 bytes)

MPC533 Pinout Diagram 5

Figure 5 shows the pinout for the MPC533.

0x30 7FFF

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_ ≥ ≸ 뮍 2 ð Щ ENGCLK_BU CLK ILS1_MPIO 32B4 CS3_0GPI 03 PULL-SEL PPM_TCLK PIO32B14_ VSSSVN EXTAL MPI032B5_ API032B9_ RXD2_ 0GPI2 XFC XTAL /SS VSS MD05 CMWMM 56 MM19_M DO7 MPI032B10_ PPM_TSYNC VFLS0_MPIO 32B3_MSE0 MPIO32B15_ PPM_TX0 CS0_SS_B_ QGPIO0 MISO_QGPI 04 MDA31 PI032B8_ VDD OVDDL VSS TEXP QQ/ /SS VDDH VSS VSS /SS N3_1 25 25 TXD1_ 0GP01 1032B11_C _CNRX0 _MPI032B _MCK0 /F2_MPI032B 2 MSEI B _B_MODC K3 06_06 ₽ CS1_QGPI01 IOSI_QGPI05 SRESET_B EXTCLK MDA30 MPWM16 BOEPEE TXD2_ OGPO2 VDD VSS VSS VSS 732B7_ WM5 VSS VSS **DD** VSS 5 24 Ē :0_MPI032 B0_MD01 WM17_M D03 M1_MD 02 32B6_ M4_MD IO32B12_ CNTX0 CS2_0GPI 02 0GPI0 CLKOUT HRE SET_ VDD VDDH RXD1_ OGPI1 VSS /SS ğ EPEE QQ VSS 0Q/ /SS /SS WDDL /SS 23 23 MDA29 MDA28 VDDH VDD ę /SS /SS VSS 22 22 IRQ5_B_S GPIOC5_M ODCK1 RO6_B_M ODCK2 MDA14 MDA15 MDA27 MDA13 VDDH VSS 5 DATA_S GPIOD14 DATA_S GPIOD16 DATA_S GPIOD17 DATA_S GPIOD18 MDA11 MDA12 TRIG2_ TRIG1_ 20 20 DATA_SGPI 0D15 DATA_SGPI 0D19 DATA_SGPI 0D20 NDDH HDDH VSS VSS 19 (As viewed from top, through the package and silicon) DATA_SG PIOD13 DATA_SG PIOD21 DATA_SG PIOD10 DATA_SG PIOD12 VSS 18 VSS VSS VSS DATA_SGP IOD11 DATA_SGP IOD22 DATA_SGP IOD23 DATA_SGP IOD8 VSS VSS VSS VSS 17 DATA_SG PIOD9 DATA_SG PIOD24 DATA_SG PIOD25 DATA_SG PIOD6 VSS VSS VSS VSS VSS 16 SS VSS VSS /SS /SS ATA_SGP IOD26 ATA_SGP IOD27 DATA_SGP IOD4 VSS VSS VSS VSS /SS /SS /SS /SS /SS /SS NVDDL 15 DATA_SG PIOD29 DATA_SG PIOD2 DATA_SG PIOD28 DATA_SG PIOD7 POA4 POA6 POA7 POA5 /SS /SS /SS /SS /SS /SS 14 DATA_SG PIOD5 DATA_SG PIOD30 DATA_SG PIOD3 MA2_PQ A2 DATA_SG PIOD0 AN55_ 2 /SS VSS /SS /SS /SS /SS 1 A1 W DATA_SG PIOD1 ADDR_SG PIOA29 DATA_SG PIOD31 ADDR_SG PIOA25 _AN48_P OB4 AN49_P OB5 AN50_F QB6 VSS VSS VSS VSS VSS VSS 12 AN51 OB7 ADDR_S SPIOA28 A_AN3_A IZ_POB3 A_AN0_A NW_PQB ADDR_S SPIOA26 ADDR_S SPIOA24 ADDR_S SPIOA27 AN2_A A_AN1_A NX_POB1 VSS VSS VSS /SS VSS /SS Ξ ADDR_SGP IOA22 DDR_SGP IOA21 ADDR_SGP IOA30 NDDL 10 NDR_SG PIOA23 NDDR_SG PIOA19 ADDR_SG PIOA31 ADDR_SG PIOA8 VSSA VSSA NVDDL 6 ADDR_SGPI 0A20 ADR_SGPI 0A16 ADDR_SGPI 0A17 ADDR_SGPI 0A9 VSS VSS VSS VSS ADDR_SG PIOA18 ADDR_SG PIOA13 ADDR_SG PIOA14 ADDR_SG PIOA15 /SS VSS VSS /SS ADDR_SGP IOA10 **VSS** VSS VSS /SS VSS VSS VSS HOO/ VSS VSS VSS /SS /SS B_CNTX0 TD0_DSD 0_MD00 IRQ1_B_R SV_B_SG PIOC1 SGPIOC6_ BR_B_VF1 _IWP2 ADDR_S. PIOA11 VDD RZ_PTR B WE_B_A1 WDDL VSS VSS CS3_B **SIZ0** BDIP_B /SS /SS /SS VSS ADDR_SG PIOA12 B_CNRX0 WP1_VFL S1 BG_B_VF 0_LWP1 WE_B_AT 2 IRQ0_B_S GPIOC0_ MD04 **DD** CS2_B rea_b TA_B NDDL VSS VSS VSS VSS VSS VSS VSS VSS /SS VSS /SS VSS K_DSCK IR02_B_C R_B_SGPI 0C2_MD0 5_MTS TMS_EVTI WP0_VFL S0 B_B_VF2 _JWP3 WE_B_AT1 B_STS_ PCS5 CS1_B VSS VDD VSS VSS VSS VSS VSS **VSS** OE_B TS_B VSS VSS INDDL VSS /SS 8 5 COMP_RS TLB IR03_B_KR _B_RETRY _B_SGPIO C3 R04_B_AT 2_SGPI0C4 rdl_dSdl_ BURST_B WE_B_AT0 RD_WR_B PCS4 CS0_B INDDL VDD NDDH TSIZ1 /SS VSS VSS VSS VSS VSS VSS LWP0 /SS /SS ROOUT ۵ S ш ш c т ≥ > AB AB Ą Ą ЧЧ Ч

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Additional MPC533 Differences

Figure 5. MPC533 Pinout Diagram

Additional MPC533 Differences

6 Supporting Documentation List

This list contains references to currently available and planned documentation.

- MPC555 User's Manual (MPC555UM/AD)
- MPC533 Reference Manual (MPC533RM/D)
- RCPU Reference Manual (RCPURM/AD)
- Nexus Standard Specification (non-Motorola document)
- Nexus Web Site: http://www.nexus5001.org/
- IEEE 1149.1 Specification (non-Motorola document)



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